

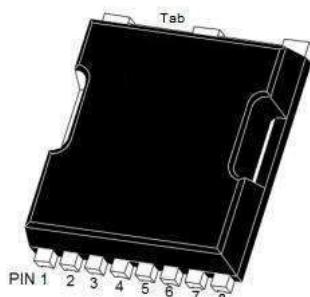
Features

- Uses MOT advanced double trench technology
- Low On-Resistance ($R_{DS(on)} \leq 1\text{m}\Omega$)
- Low Gate Charge
- Low Reverse transfer capacitances
- 100% avalanche tested
- Pb-free plating; RoHS compliant

Applications

- Battery management
- Motor control and drive
- Synchronous rectification
- Switching applications

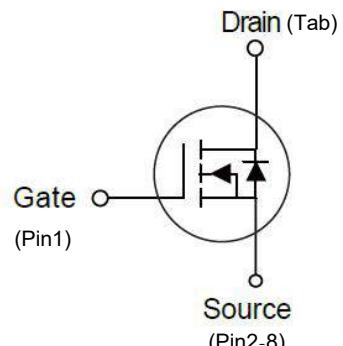
Pin configuration (Top view)



□

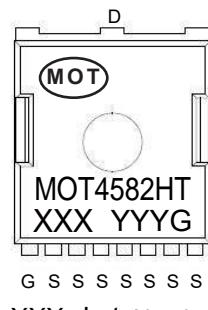
TOLL-8

Symbol



Key Performance Parameters

Parameter	Value	Unit
V_{DS}	40	V
$R_{DS(on)}$,typ.	0.85	$\text{m}\Omega$
I_D	395	A



Marking

Ordering information

Type/Ordering Code	Package	Marking	Packing&Qty.(pcs)
MOT4582HT	TOLL-8	MOT4582HT	2000/Reel

■ ABSOLUTE MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	395	A
Drain Current-Continuous($T_c=100^\circ\text{C}$)	$I_D (100^\circ\text{C})$	249	A
Pulsed Drain Current	I_{DM}	1582	A
Maximum Power Dissipation	P_D	250	W
Thermal Resistance,Junction-to-Case	$R_{\theta JC}$	0.5	$^\circ\text{C}/\text{W}$
Single pulse avalanche energy	E_{AS}	3081	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$

■ ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	40	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On characteristics						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=75\text{A}$	-	0.85	1.0	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=5\text{A}$	-	22	-	S
Dynamic characteristics						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=20\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $F=1.0\text{MHz}$	-	6300	-	pF
Output Capacitance	C_{oss}		-	4400	-	pF
Reverse Transfer Capacitance	C_{rss}		-	1900	-	pF
Switching characteristics						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=20\text{V}, \text{I}_D=20\text{A}$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_G=1.6\Omega$	-	25	-	nS
Turn-on Rise Time	t_r		-	48	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	75	-	nS
Turn-Off Fall Time	t_f		-	30	-	nS
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=20\text{V}, \text{I}_D=20\text{A},$ $\text{V}_{\text{GS}}=10\text{V}$	-	130	-	nC
Gate-Source Charge	Q_{gs}		-	27	-	nC
Gate-Drain Charge	Q_{gd}		-	30	-	nC
Drain-source diode characteristics						
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=20\text{A}$	-	-	1.2	V
Diode Forward Current	I_s		-	-	353	A
Reverse Recovery Time	t_{rr}	$\text{T}_J = 25^\circ\text{C}, \text{I}_F = 20\text{A}$	-	98	-	nS
Reverse Recovery Charge	Q_{rr}	$\text{di}/\text{dt} = 100\text{A}/\mu\text{s}$	-	64	-	nC

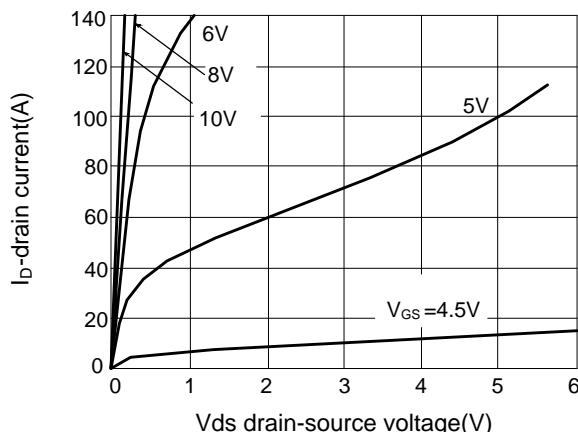
■ TYPICAL CHARACTERISTICS


Figure 1: Output characteristics

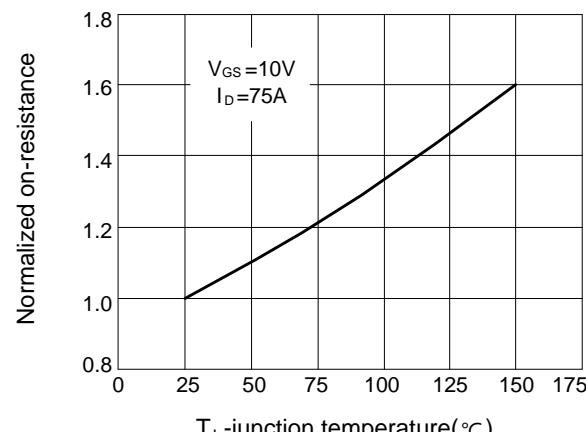
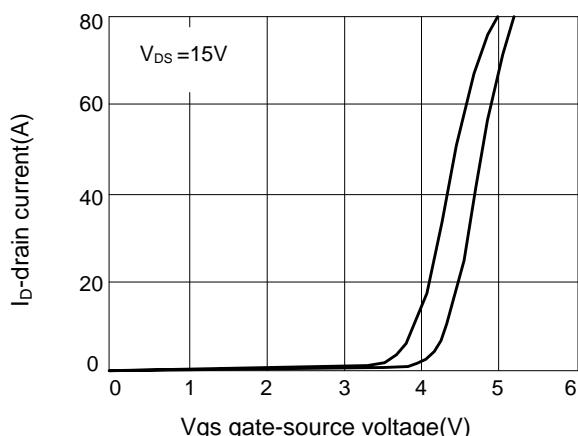

 Figure 2: $R_{DS(on)}$ -junction temperature


Figure 3: Transfer characteristics

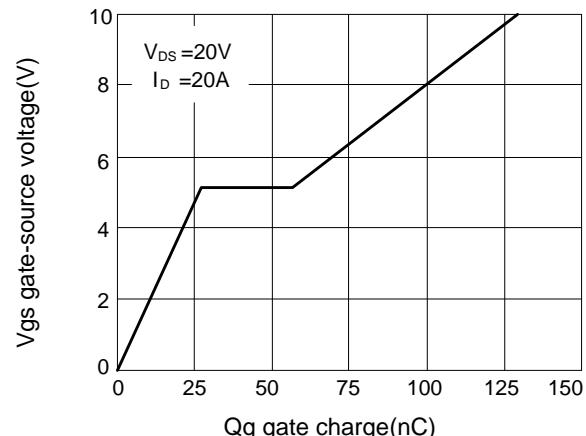


Figure 4: Gate charge

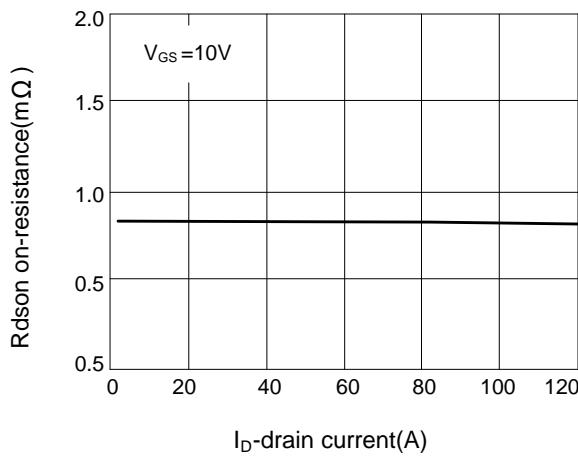
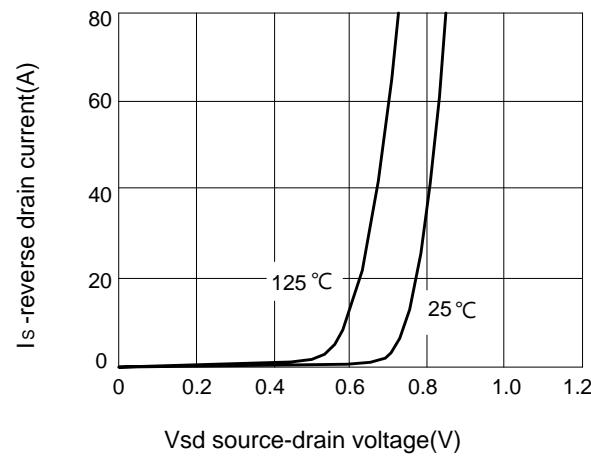

 Figure 5: $R_{DS(on)}$ -drain current


Figure 6: Source -drain diode forward

■ TYPICAL CHARACTERISTICS(Cont.)

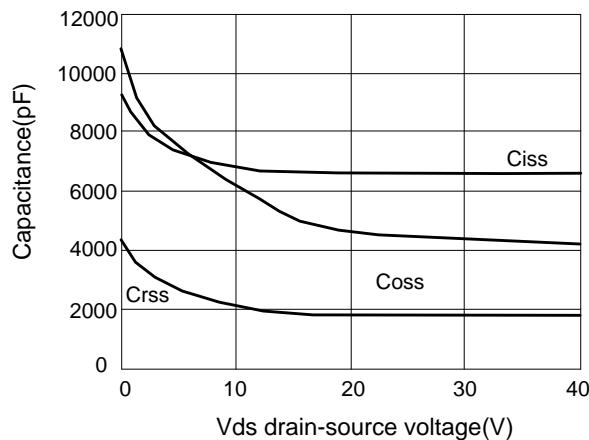


Figure 7: Capacitance vs vds

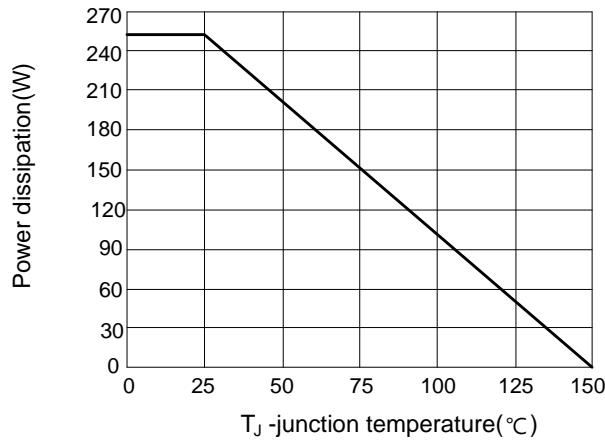


Figure 8: Power de-rating

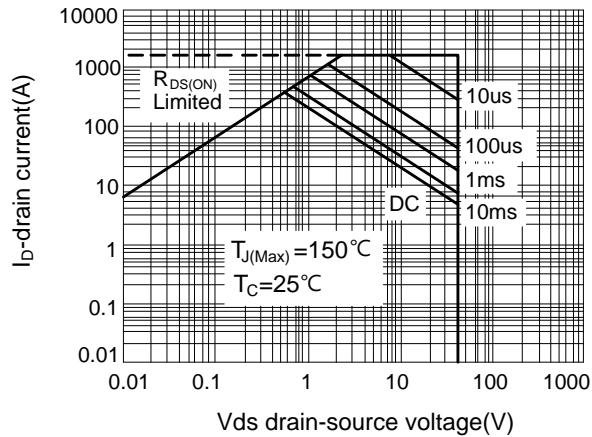


Figure 9: Safe operation area

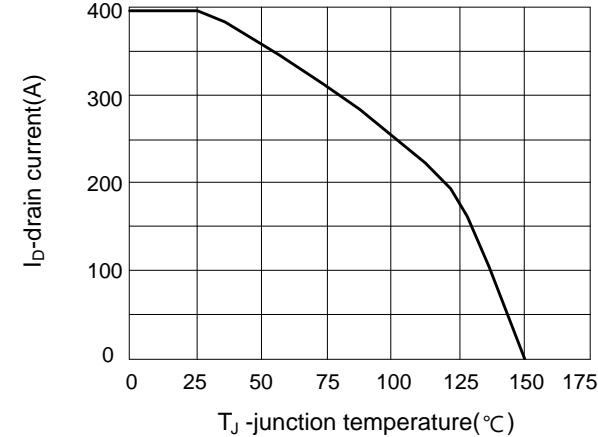
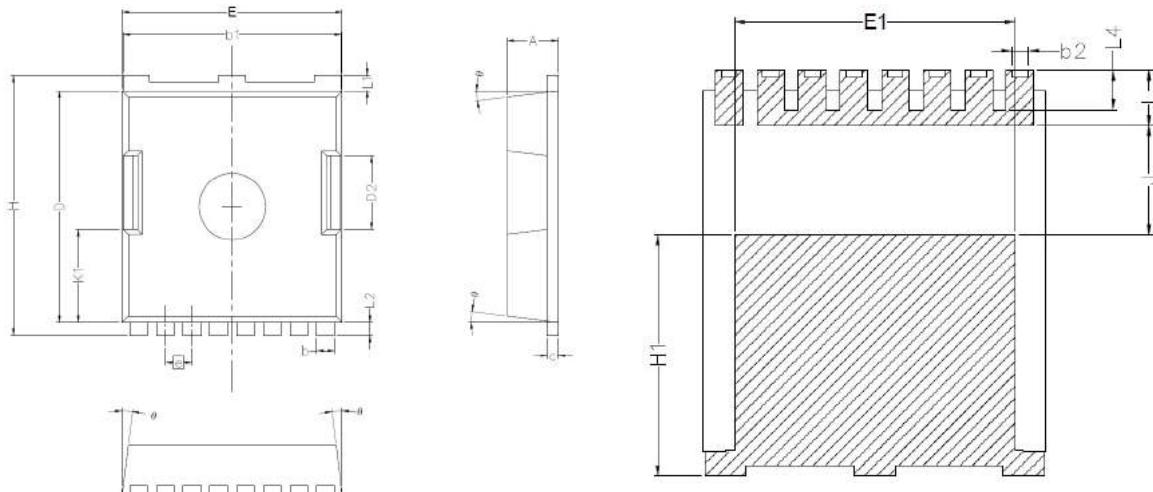


Figure 10: Current de-rating

■TOLL-8L PACKAGE OUTLINE DIMENSIONS


Symbol	Dimensions In Millimeters	
	Min.	Max.
A	2.20	2.40
b	0.70	0.90
b1	9.70	9.90
b2	0.42	0.50
c	0.40	0.60
D	10.28	10.58
D2	3.10	3.50
E	9.70	10.10
E1	7.90	8.30
e	1.20BSC	
H	11.48	11.88
H1	6.75	7.15
N	8	
J	3.00	3.30
K1	3.98	4.38
L	1.40	1.80
L1	0.60	0.80
L2	0.50	0.70
L4	1.00	1.30
θ	4°	10°

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